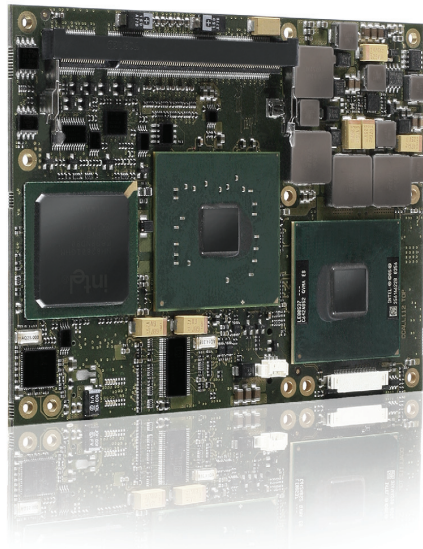


» COMe-bCD2 «



COM Express® basic up to Intel® Core™ Duo processor

- » Up to 4 GB DDR2 memory
- » 2x SerialATA, 8x USB 2.0
- » Up to 4 PCI Express x1 and PEG x16
- » Gigabit Ethernet for high connectivity

The COMe-bCD2 module is based on up to the Intel® Core™ Duo processor as well as the Intel® 945GME chipset. PCI Express is the primary data path for upcoming x86 based systems. Non PCI Express components such as PCI plug-in cards can still be supported with the PCI 2.1 32 Bit Interface.

The COMe-bCD2 will support 4 PCI Express x1, PEG x16 lanes. Gigabit Ethernet for high connectivity and 8x USB 2.0 provides fast and sufficient interfaces for external peripherals. COM

Express® basic modules also will provide interfaces that are always located in the same physical position on each board, thus guaranteeing scalability between modules. Six mounting holes on the board provide increased shock and vibration resistance.

Technical Information

Processor	Up to Intel® Core™ Duo processor up to 1,66 GHz Intel® Celeron® M 1.06 GHz and 1.86 GHz
Chipset	Intel® 945GME, ICH7M-DH
Memory	Physical memory up to 4 GB (533/667) DDR2 SODIMM by dual channel memory support
Hard Disk	2x SerialATA (AHCI/RAID 0,1), 1x PATA
USB	8x USB 2.0 ports
PCI Express	4 PCI Express x1 (1 PCI Express x4 possible); 1 PEG x16
PCI	PCI 2.3, 32 bit / 33 MHz PCI bus
Ethernet	10/100/1000 MBit Ethernet, Realtek RTL8111C
Sound	Intel® High Definition Audio / AC 97
Graphics Controller	Integrated with Intel® Graphics Media Accelerator (GMA950) with DirectX® 9.0/SM3.0 and DVMT 3.0 support; Dual SDVO multiplexed with PEG
Display Interfaces	CRT up to 2048 x 1536, LVDS up to 1600 x 1200, (JILI3 / EDID support), Single and Dual Channel LVDS 18/24 bit TV out (Component, S-Video, Composite), HDTV support (1080p)
Other Features	LPC, JIDA Support, WakeOnLAN, Watchdog, I²C Bus, RTC, 8 GPIO, LAN Boot, JRC support, Suspend states (S0/S3/S4/S5), ACPI
Form Factor / Pin-out Type	125 x 95 mm COM Express® basic, COM Express® Pin-out Type 2
Power Consumption	Typ. Idle 11W @ Intel® Core™ Duo processor L2400LV 8,5 V – 18 V Wide Range Power Supply
Temperature	Operation: 0°C to 60°C (-25°C to 75°C available) Storage: -30°C to 85 °C
Humidity	Operation: 10% to 90% Storage: 5% to 95% (non condensing)

Ordering Information

Article	Part No.	Description
COMe-bCD2 Dual Channel	38003-0000-11-4	Intel® Celeron® M ULV 423 (1.06GHz, 533FSB, 1MB L2), up to 4GB DDR2
COMe-bCD2 Dual Channel	38003-0000-17-5	Intel® Core™ Duo L2400 LV (1.66GHz, 667FSB, 2MB L2), up to 4GB DDR2
COMe-bCD2 Dual Channel	38003-0000-19-4	Intel® Celeron® M 440 (1.86GHz, 533FSB, 1MB L2), up to 4GB DDR2
HSP-COMe-bCD2 threaded	38003-0000-99-0	Heatspreader for COMe-bCD2, threaded mounting holes
HSP-COMe-bCD2 through	38003-0000-99-1	Heatspreader for COMe-bCD2, through holes
HSK COMe-bCD2 active thread	38003-0000-99-0C01	Active cooling solution for COMe-bCD2, threaded mounting holes
HSK COMe-bCD2 passive thread	38003-0000-99-0C02	Passive cooling solution for COMe-bCD2, threaded mounting holes

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